

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6342	(257/758,700,701,702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/28 14:51
L2	1836	(361/750,748,749,751).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 14:51
L3	6453	L1 or L2 and laminat\$3 and interconnect\$3 and polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/28 14:51
L5	12	((("5074947") or ("5237130") or ("5611140") or ("5761048") or ("5910641") or ("6199751") or ("6259036") or ("6297559") or ("6331119") or ("6337522") or ("6425772") or ("6512183"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/28 14:57
S1	4061	(257/758,759,760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 09:05
S2	6304	(257/758,700,701,702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 09:07
S13	6312	(257/758,700,701,702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/26 09:38
S14	1835	(361/750,748,749,751).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/16 12:40
S15	6423	S13 or S14 and laminat\$3 and interconnect\$3 and polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/28 14:51

S16	1630	S15 and ( resin or thermoplastic or thermoset)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/13 11:01
S17	165	S16 and metal\$3 and (cube or cylind\$5 or cone or conical)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/13 09:14
S18	37	S15 and (thermoplastic or thermoset) and (alternat\$3 near1 (layer or side) and metal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/13 14:15
S19	20	S15 and (thermoplastic and thermoset) and (alternat\$3 near1 (layer or side) and metal\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/13 14:48
S21	30	(S13 or S14) and interconnect\$3 and metal and project\$3 and (sphere or spher\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/13 16:47
S22	17	(S13 or S14) and interconnect\$3 and metal and project\$3 and (sphere or spher\$4) and polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/13 16:52
S23	86	(S13 or S14) and interconnect\$3 and metal and project\$3 and (sphere or spher\$4 or circ\$4) and polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/13 16:53
S25	2	S15 and (sphere or spherical or circle or circular) near polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/22 12:54
S26	3	S15 and (sphere or spherical or circle or circular) near3 polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/13 17:03
S28	4069	(257/758,759,760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/14 09:40

S29	6312	(257/758,700,701,702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/14 09:40
S30	1835	(361/750,748,749,751).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/14 09:40
S32	7	(S28 or S29 or S30) and ((cone or conical) or (triang\$4)) and (sphere or spherical near3 polymer3) and metal	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/14 10:08
S33	1396	(S28 or S29 or S30) and polymer\$3 and metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/14 12:40
S34	57	S33 and (sphere or spherical near3 polymer\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/14 10:20
S35	33	S33 and (sphere or spherical near3 polymer\$3) and interconnect\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/14 10:41
S39	20	(S28 or S29 or S30) and polymer\$2 and dendrit\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/14 14:38
S43	4073	(257/758,759,760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 07:32
S44	6317	(257/758,700,701,702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 07:32
S46	4073	(257/758,759,760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:58

S47	6317	(257/758,700,701,702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 13:58
S48	1835	(361/750,748,749,751).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/15 13:58
S49	24	(S46 or S47 or S48) and laminat\$3 and interconnect\$3 and (alternat\$3 near3 (metal or polymer)) and metal and polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/15 14:20
S50	13	(S46 or S47 or S48) and laminat\$3 and interconnect\$3 and (alternat\$3 near3 (metal or polymer)) and device and carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/15 15:00
S52	4073	(257/758,759,760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 12:41
S53	6317	(257/758,700,701,702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 12:41
S54	1835	(361/750,748,749,751).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/16 12:41
S58	288	(polymer with spher\$4 and (die chip IC (integrated adj circuit)) and (interconnect interconnection))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/16 16:23
S59	288	(polymer with spher\$4 and (die chip IC (integrated adj circuit)) and (interconnect interconnection))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/16 16:26
S60	6324	(257/758,700,701,702).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/21 17:19

S61	1835	(361/750,748,749,751).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/21 17:19
S62	100	(S60 or S61) and laminat\$3 and interconnect\$3 and polymer and metal and (die integratedadj circuit IC chip device) and carrier and alternat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/21 17:52
S63	22	(S60 or S61) and laminat\$3 and interconnect\$3 and conduct\$3 near polymer and metal and alternat\$3 and (die integrated adj circuit IC chip device) and carrier	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/21 17:53
S65	1834	(257/738,739).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/09/22 12:55
S72	1164	dendrit\$2 and plate and conduct\$3 and spher\$4 and polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/26 12:07
S78	343	dendrit\$3 and polymer and conduct\$3 and (irregular nonperiodic) and spher\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/09/26 12:52